

# H5N3005LD, H5N3005LS, H5N3005LM

# Silicon N Channel MOS FET High Speed Power Switching

REJ03G1315-0400 Rev.4.00 Nov 08, 2005

#### **Features**

- Low on-resistance
- Low leakage current
- www.DataSheet U.High speed switching

#### **Outline**

RENESAS Package code: PRSS0004AE-A (Package name LDPAK(L))

RENESAS Package code: PRSS0004AE-B (Package name LDPAK(S)-(1))

RENESAS Package code: PRSS0004AE-C (Package name LDPAK(S)-(2))

H5N3005LD

RENESAS Package code: PRSS0004AE-C (Package name LDPAK(S)-(2))

H5N3005LS

H5N3005LM

1. Gate 2. Drain 3. Source 4. Drain

# **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Ratings	Unit
Drain to source voltage	V <sub>DSS</sub>	300	V
Gate to source voltage	V <sub>GSS</sub>	±30	V
Drain current	I <sub>D</sub>	15	Α
Drain peak current	I <sub>D (pulse)</sub> Note1	60	Α
Body-drain diode reverse drain current	I <sub>DR</sub>	15	Α
Body-drain diode reverse drain peak current	I <sub>DR (pulse)</sub> Note1	60	Α
Avalanche current	I <sub>AP</sub> Note3	15	Α
Avalanche energy	E <sub>AR</sub> Note3	13.5	mJ
Channel dissipation	Pch Note2	75	W
Channel to case thermal impedance	θch-c	1.67	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1%

2. Value at Tc = 25°C

3. STch =  $25^{\circ}$ C, Tch  $\leq 150^{\circ}$ C

# **Electrical Characteristics**

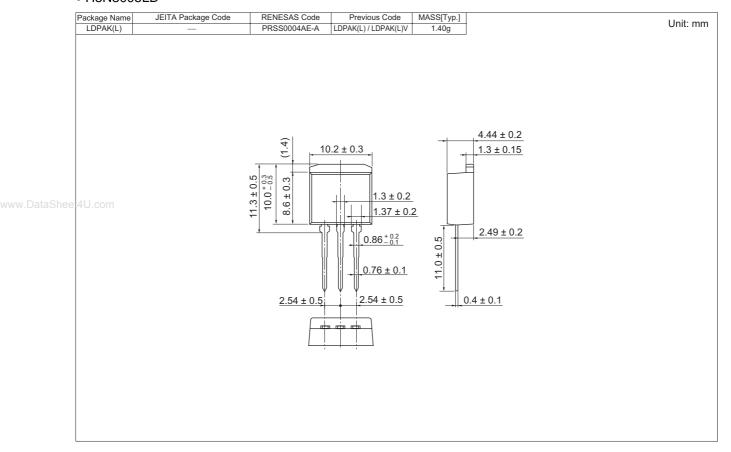
 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	300	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 300 \text{ V}, V_{GS} = 0$
Gate to source leak current	I <sub>GSS</sub>	_	_	±0.1	μΑ	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	3.0	_	4.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Forward transfer admittance	y <sub>fs</sub>	7	12	_	S	$I_D = 7.5 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$
Static drain to source on state	R <sub>DS(on)</sub>	_	0.210	0.255	Ω	$I_D = 7.5 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note4}}$
resistance						
Input capacitance	Ciss		1300	_	pF	V <sub>DS</sub> = 25 V
Output capacitance	Coss		155		pF	V <sub>GS</sub> = 0 f = 1 MHz
Reverse transfer capacitance	Crss	_	50	_	pF	
Turn-on delay time	t <sub>d(on)</sub>	_	30	_	ns	I <sub>D</sub> = 7.5 A
Rise time	t <sub>r</sub>	_	30	_	ns	$V_{GS} = 10 \text{ V}$ $R_L = 20 \Omega$ $Rg = 10 \Omega$
Turn-off delay time	t <sub>d(off)</sub>	_	90	_	ns	
Fall time	t <sub>f</sub>	_	15	_	ns	
Total gate charge	Qg	_	49	_	nC	V <sub>DD</sub> = 240 V
Gate to source charge	Qgs	_	8	_	nC	V <sub>GS</sub> = 10 V I <sub>D</sub> = 15 A
Gate to drain charge	Qgd	_	25	_	nC	
Body-drain diode forward voltage	$V_{DF}$	_	0.86	1.30	V	$I_F = 15 \text{ A}, V_{GS} = 0^{\text{Note4}}$
Body-drain diode reverse recovery time	t <sub>rr</sub>	_	190	_	ns	I <sub>F</sub> = 15 A, V <sub>GS</sub> = 0
Body-drain diode reverse recovery	Q <sub>rr</sub>	_	1.3	_	μС	di <sub>F</sub> /dt = 100 A/μs
charge						

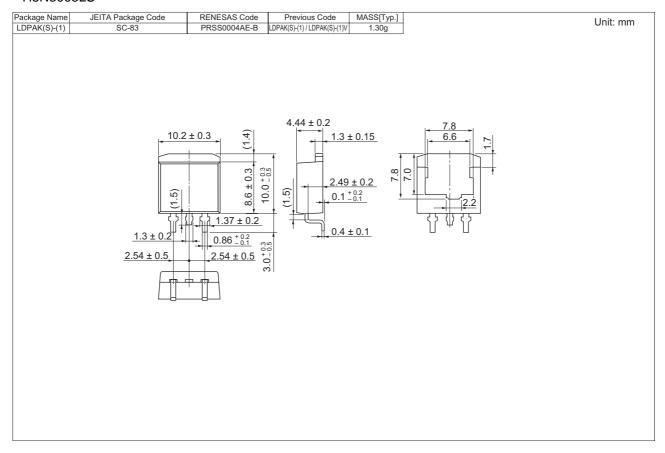
Notes: 4. Pulse test

# **Package Dimensions**

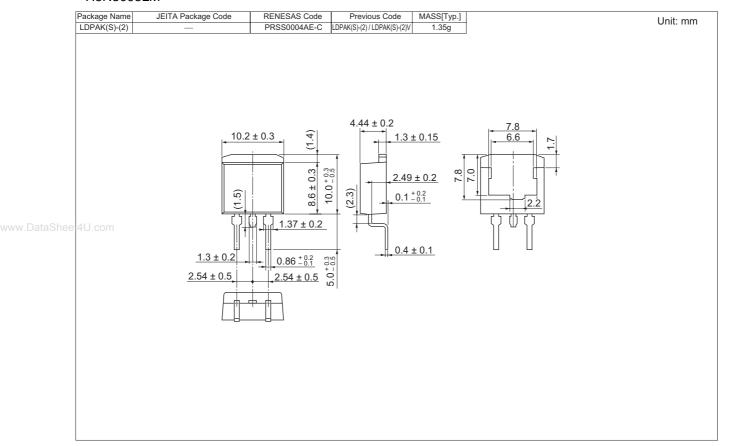
### • H5N3005LD



#### • H5N3005LS



### • H5N3005LM



# **Ordering Information**

Part Name	Quantity	Shipping Container
H5N3005LSTL-E	1000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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